

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	50263	dicing or diced or sawing	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:51
L2	85994	(groove\$1 or recess\$2 or trench\$2 or hole\$1) near6 etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:52
L3	2109787	polymer\$5 or resin or epoxy or epoxies	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:52
L4	493993	etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:52
L5	588326	thinning or thinned or polish\$3 or cmp or grind\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:53
L6	895113	(through-hole\$1 or through) near6 (via or vias or contact\$1 or conduct\$1 or metal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:55
L7	6882	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 15:56
L8	242	1 and 7 and 5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:17
L9	443	1 and 7 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:17
L10	201	9 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:41

L11	443	8 or 9 or 10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:41
L12	393159	"438"/\$.ccls. or "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:41
L13	224	11 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:42
L14	5116	1 and 2 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:45
L15	2107859	pin\$1 or stud\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:45
L16	899037	6 or 7	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:45
L17	2186847	chip\$1 or die or (integrated adj circuit\$1) or ic or (semiconduct\$3 adj2 device\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:46
L19	4389	14 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:47
L21	2708	19 and (6 or 15)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:49
L22	1644	21 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:49

L23	999	22 and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:49
L24	832	23 not 11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/13 16:50